

Low Vcesat PNP Epitaxial Planar Transistor

Features

- Low VCE(sat)
- Excellent current gain characteristics
- Complementary to KJD1760
- Pb-free lead plating and halogen-free package

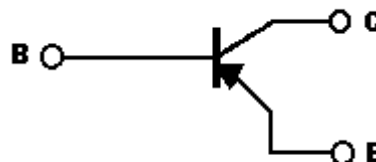
Outline

TO-252(DPAK)



Symbol

KJB1184



B : Base
 C : Collector
 E : Emitter

Ordering Information

Device	Package	Shipping
KJB1184	TO-252 (RoHS compliant and halogen-free package)	2500 pcs / Tape & Reel

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EBO}	-6	V
Collector Current(DC)	I _C	-3	A
Collector Current(Pulse)	I _{CP}	-7 *1	
Power Dissipation (T _A =25°C)	P _d (T _A =25°C)	1	W
Power Dissipation (T _C =25°C)	P _d (T _C =25°C)	15 *2	
Thermal Resistance, Junction to Ambient	R _{θJA}	125	°C/W
Thermal Resistance, Junction to Case	R _{θJC}	8.33 *2	
Operating Junction and Storage Temperature Range	T _j ,T _{stg}	-55~+150	°C

Note : *1. Single Pulse P_w=10ms

*2 . Printed circuit board, 1.7mm thick, collector copper plating 10mm*10mm or larger.

Characteristics (Ta=25°C)

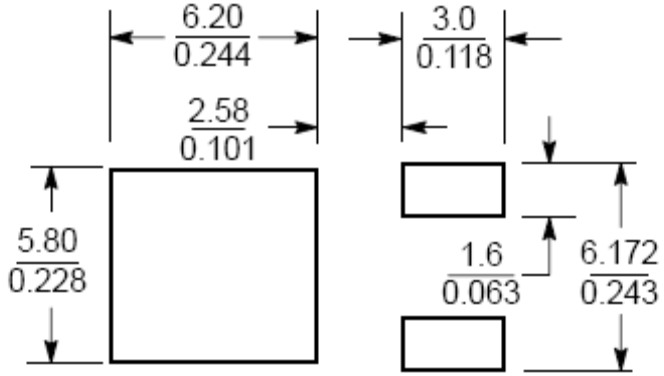
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	-60	-	-	V	I _C =-50μA, I _E =0
BV _{CEO}	-50	-	-	V	I _C =-1mA, I _B =0
BV _{EBO}	-6	-	-	V	I _E =-50μA, I _C =0
I _{CBO}	-	-	-1	μA	V _{CB} =-40V, I _E =0
I _{EBO}	-	-	-1	μA	V _{EB} =-4V, I _C =0
*V _{CE(sat)}	-	-0.26	-0.5	V	I _C =-2A, I _B =-0.1A
*V _{BE(sat)}	-	-0.96	-1.2	V	I _C =-2A, I _B =-0.1A
*h _{FE1}	120	-	-	-	V _{CE} =-2V, I _C =-20mA
*h _{FE2}	180	-	560	-	V _{CE} =-3V, I _C =-500mA
*h _{FE3}	80	-	-	-	V _{CE} =-2V, I _C =-1A
f _T	-	80	-	MHz	V _{CE} =-5V, I _C =-0.1A, f=100MHz
Cob	-	35	-	pF	V _{CB} =-10V, f=1MHz

*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

Classification Of h_{FE2}

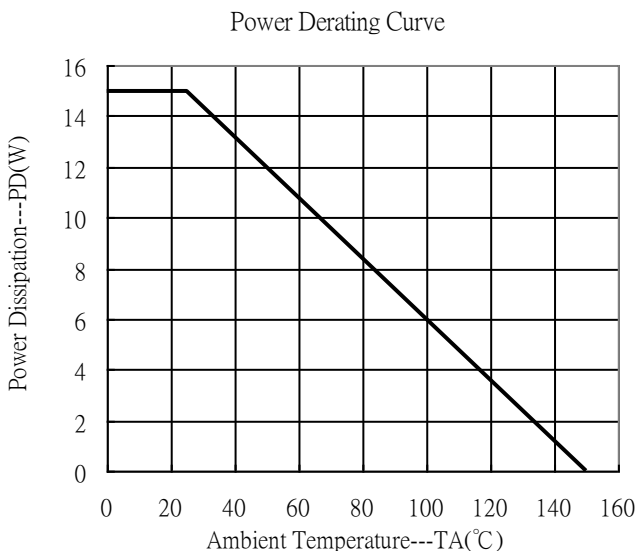
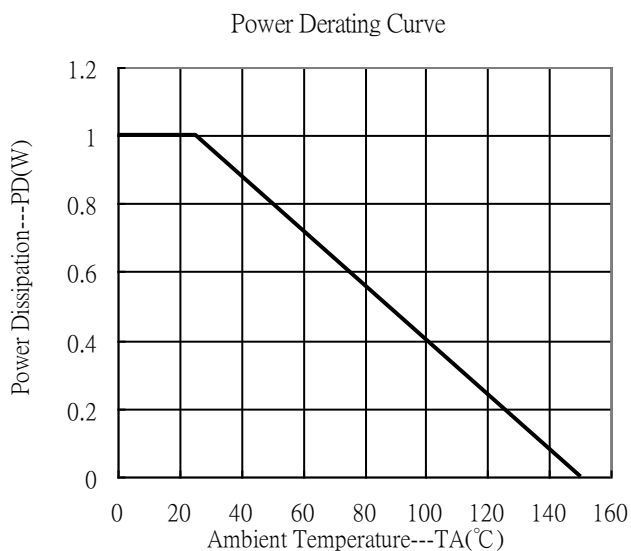
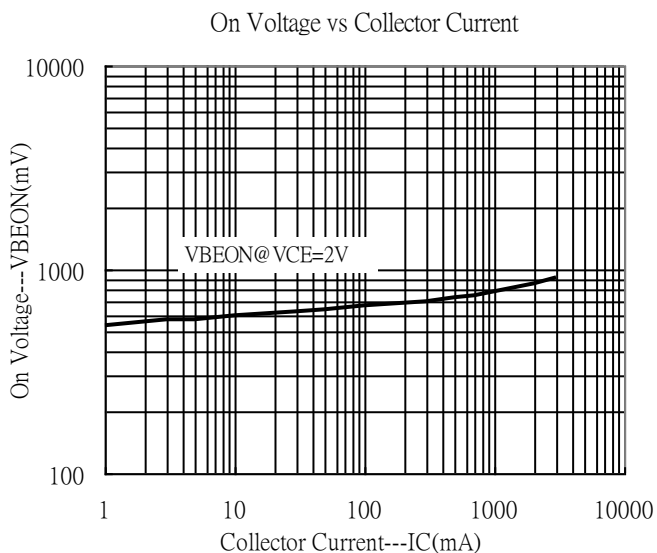
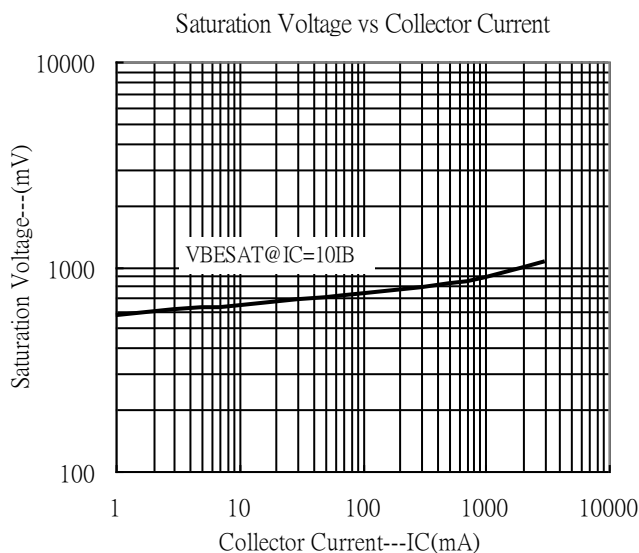
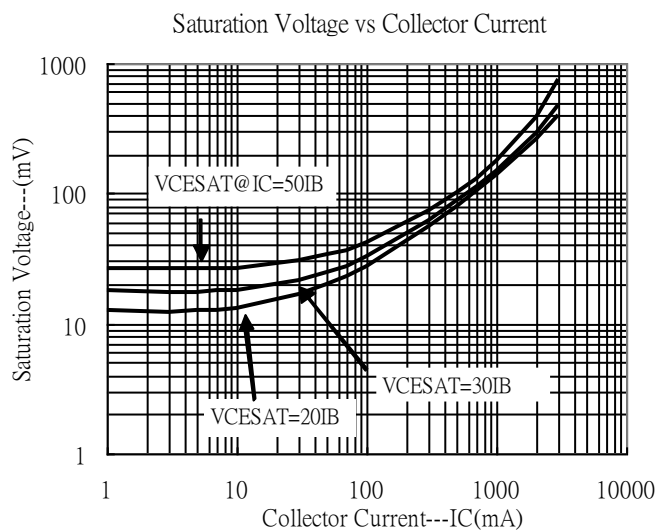
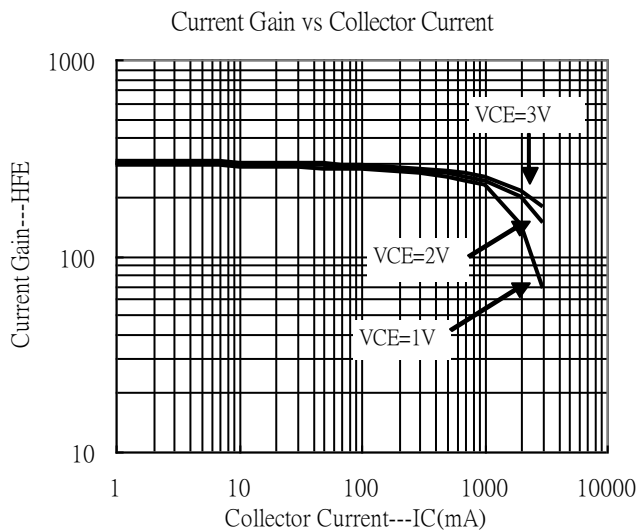
Rank	R	S
Range	180~390	270~560

Recommended soldering footprint

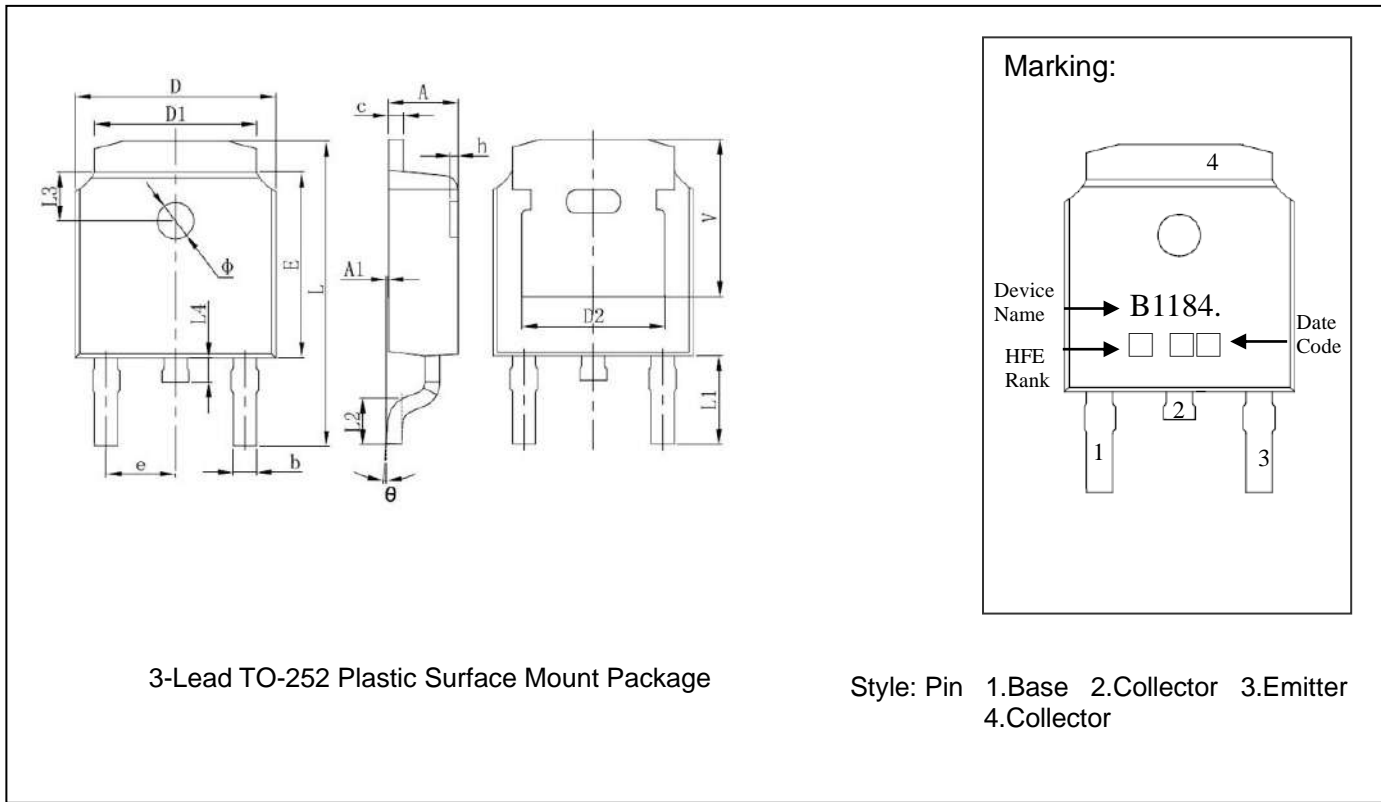


Unit ($\frac{\text{mm}}{\text{inch}}$)

Typical Characteristics



TO-252 Dimension



The image contains three diagrams: a top view with dimensions D, D1, L3, L4, L, L1, e, b, and ϕ ; a side view with dimensions A, A1, c, h, and θ ; and a bottom view with dimensions D2 and V. To the right is a 'Marking:' diagram showing a top-down view of the package with pins 1, 2, 3, and 4. It indicates the 'Device Name' as 'B1184.', the 'HFE Rank' as three squares, and the 'Date Code' as two squares.

3-Lead TO-252 Plastic Surface Mount Package

Style: Pin 1.Base 2.Collector 3.Emitter 4.Collector

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372 ⁴	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF